



Middle Tg, Halogen Free & Low Flow Prepreg EM-285B(L)

- Excellent thermal resistance
- Dust-free for punching processing
- Stable flow performance
- Shelf life is as long as normal prepreg(90days)
- For rigid-flex board PCB design application

Basic Prepreg Property

Item	IPC-TM-650	Test Condition	Unit	Typical Value	
Flow in	2.3.17.2	-	mil	<25	
				25~80	
Glass Transition Temp.	2.4.25	DSC	°C	150	
Glass Transition Temp.	2.4.24.5	DMA	°C	160	
CTE, Z-axis	2.4.24	Alpha 1, TMA	ppm/°C	45	
		Alpha 2, TMA	ppm/°C	290	
Decomposition Temp.	2.4.24.6	TGA	°C	375	
Thermal Stress 10sec 288°C (Core +PP+PI)	-	Clad	cycle	>10	
Peel Strength	Hoz Cu	2.4.8	As Received	lb/in	7.5
	Coverlay	-	As Received	lb/in	8.0
Permittivity (RC 75%)	1 MHz	2.5.5.9	C-24/23/50	-	4.1
	1 GHz			-	3.7
Loss Tangent (RC 75%)	1 MHz	2.5.5.9	C-24/23/50	-	0.011
	1 GHz			-	0.016